

Abstract

In the case of an apparatus and a process for moulding microsystem structures, the object is to compensate for variations in thickness of moulding tools and of mouldable materials used in an embossing process to be carried out under a vacuum, while ensuring high dimensional stability, and to ensure different moulding depths.

According to the invention, a chamber having a pair of oppositely lying chamber parts, of which one is fixed to the framework and the other is adjustable, has side walls which comprise an inner part and an outer part. The inner part is fastened to the fixed chamber part and the outer part, on the outwardly facing end face of which the adjustable chamber part comes to bear against the force of a spring during the closing of the chamber, is displaceable along guide elements on the fixed chamber part between two stops.

Within the chamber there takes place a setting of atmospheric conditions and of temperature conditions at points in time of the closing of the chamber at which an increase in a force acting on the fixed chamber part reaches predetermined values.

The invention can be used in the production of microsystem components.

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